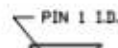


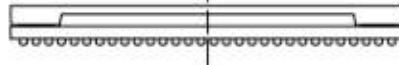
FF900/901 - Pb/Sn SOLDER BALLS
 FFG900/901 - Sn/Ag/Cu SOLDER BAL
 FFV900/901 - Sn/Ag/Cu SOLDER BAL

MILLIMETERS			NOTE
MIN.	NOM.	MAX.	
2.95	3.15	3.35	4
0.40	0.50	0.60	
2.55	~	2.75	
31.00 BASIC			
29.00 REF			
1.00 BASIC			
0.50	0.60	0.70	
~	~	0.20	
~	~	0.35	
~	~	0.30	
30			2



OPTION 'A'
 FOR FFG/FFV901

4 CORNER POST LID - OPTION 5
 (SAME THICKNESS DIMENSION)



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. CONFORMS TO JEDEC MS-034-AAN-1
4. ACTUAL SOLDER BALL COUNT = 900

5 4 CORNER POST LID IS USED FOR FFG/FFV901

ug475_c04_05_071

FF900, FFG900, FFV900, FF901, FFG901, and FFV901 Flip-Chip BGA Package Specif